

ABSTRACT

Sub 191
5 The main purpose of the present invention is to provide a method of removing plating blocking ions such as anions in pairs with copper ions and oxidant ions of the copper ion reducing agent from the electroless copper plating solution and keeping a constant salt concentration in the electroless copper plating solution during plating, a device to realize said method, and applications thereof.

10 For An electroless copper plating method, a device thereof, and application thereof, using a plating solution containing copper sulfate as copper ion sources, and a copper ion complexing agent as copper ion sources, glyoxylic acid as a copper ion
15 reducing agent, and pH conditioner, the present invention is characterized by precipitating and removing sulfuric and oxalic ions in said electroless copper plating solution and keeping an optimum concentration of at least one of sulfuric and oxalic
20 ions in said electroless copper plating solution during plating.

004007 0082960